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(71) Applicant (for all designated States except US): **AGENCY FOR SCIENCE, TECHNOLOGY AND RESEARCH** [SG/SG]; 1 Fusionopolis Way #20-10, Connexis, Singapore 138632 (SG).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **YU, Daquan** [CN/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG). **PARK, Woo Tae** [KR/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG). **LIM, Li Shiah** [MY/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG). **HAMIDULLAH, Muhammad** [ID/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG). **KOT-LANKA, Rama Krishna** [IN/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG).

KRIPESH, Vaidyanathan [IN/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG). **FENG, Hanhua** [SG/SG]; c/o Industry Development, Institute of Microelectronics, 11 Science Park Road, Singapore Science Park 2, Singapore 117685 (SG).

(74) Agent: **VIERING, JENTSCHURA & PARTNER LLP**; P.O. Box 1088, Rochor Post Office, Rochor Road, Singapore 911833 (SG).

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(54) Title: GUIDE WIRE ARRANGEMENT, STRIP ARRANGEMENT AND METHODS OF FORMING THE SAME

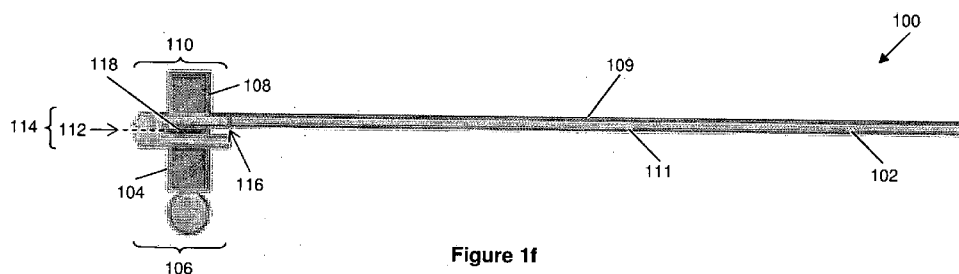


Figure 1f

(57) Abstract: A guide wire arrangement, a strip arrangement, a method of forming a guide wire arrangement, and a method of forming a strip arrangement are provided. The guide wire arrangement includes a strip; a sensor being disposed on a first portion of the strip; a chip being disposed next to the sensor on a second portion of the strip, wherein the second portion of the strip is next to the first portion of the strip; wherein the strip is folded at a folding point between the first portion of the strip and the second portion of the strip such that the first portion of the strip and the second portion of the strip form a stack of strip portions.

